

| Corrosion Reliability of Electronic Devices | |
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| 11:00 – 12:40 | Room: Galerie A |
| Chairs | R. Ambat, Technical University of Denmark Lyngby/DK H. Schweigart, Zestron Europe, Ingolstadt/DE |
| 11:00 – 11:20 | Corrosion reliability of electronics: prediction, prevention, and control R. Ambat, Technical University of Denmark, Lyngby/DK |
| 11:20 – 11:40 | Corrosion prevention by assembly design H. Schweigart, Zestron Europe, Ingolstadt/DE |
| 11:40 – 12:00 | Phosphorous based flame retardants for polyamides and corrosion L. Müller ¹ , H. Steffes ² ¹ Robert Bosch GmbH, Reutlingen/DE; ² Bosch Power Tec GmbH, Böblingen/DE |
| 12:00 – 12:20 | Effect of iodine on the corrosion of Au-Al wire bond interconnects V. Verdingovas ¹ , L. Müller ² , M. Stendahl Jellesen ¹ , R. Ambat ¹ ¹ Technical University of Denmark, Lyngby/DK; ² Robert Bosch GmbH, Reutlingen/DE |
| 12:20 – 12:40 | Cost-efficient feed-throughs with polymers – Interphase design, benchmarking & tightness A. Holm ¹ , J. Jacobsen ¹ , J. Krog ¹ , A. Riis ¹ , J. Harming ¹ , L. Rimestad ¹ ¹ Grundfos Holding A/S, Bjerringbro/DK |

| 12:40 – 14:00 | LUNCH BREAK / Room: Exhibition Area |
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| Corrosion Reliability of Electronic Devices | |
| 14:00 – 15:40 | Room: Galerie A |
| Chair | R. Ambat, Technical University of Denmark, Lyngby/DK |
| 14:00 – 14:20 | Formation of semiconductive electrochemical migration S. Mattern ¹ , L. Henneken ¹ , M. Nowotnick ² ¹ Robert Bosch GmbH, Schwieberdingen/DE; ² Universität Rostock, Rostock/DE |
| 14:20 – 14:40 | Corrosion of printed circuit board assemblies (PCBAs) – Field experience and counter measures J.-H. Klingel, Kunststoff-Chemische Produkte GmbH, Frielzheim/DE |
| 14:40 – 15:00 | Contamination, potential bias and humidity effects on electrical performance and corrosion reliability of electronic devices K. Piotrowska ¹ , V. Verdingovas ¹ , M. Stendahl Jellesen ¹ , R. Ambat ¹ ¹ Technical University of Denmark, Lyngby/DK |
| 15:00 – 15:20 | Experimental study of humidity distribution inside an electronic enclosure and effect of internal heating H. Conseil ¹ , M. Jellesen ¹ , R. Ambat ¹ ¹ Technical University of Denmark, Lyngby/DK |
| 15:20 – 15:40 | Humidity related failure mechanisms and corresponding tests K. Schmidt ¹ , A. Kentved ¹ ¹ DELTA, Hoersholm/DK |
| 15:40 – 16:10 | COFFEE BREAK / Room: Exhibition Area |
| Corrosion Reliability of Electronic Devices | |
| 16:10 – 16:50 | Room: Galerie A |
| Chair | H. Schweigart, Zestron Europe, Ingolstadt/DE |
| 16:10 – 16:30 | Thermal effects in electronic systems as an implication of electrochemical corrosion F. Petri, Robert Bosch GmbH, Reutlingen/DE |
| 16:30 – 16:50 | Sulphur induced corrosion of electronics M. Jellesen ¹ , V. Verdingovas ¹ , S. Davidsdottir ¹ , R. Ambat ¹ ¹ Technical University of Denmark, Lyngby/DK |